Product Change Notification: MFOL-15RYZV597

Date:

17-Sep-2026

Product Category:

Platform Root Of Trust Controllers

Notification Subject:

CCB 7657 Final Notice: Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

Affected CPNs:

MFOL-15RYZV597_Affected_CPN_09172026.pdf
MFOL-15RYZV597_Affected_CPN_09172026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change** (Yes/No)
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Yes

Substrate Core Material	HL832NXA	HL832NXA	HL832NXA	No
Substrate SM Material	AUS320	AUS320	AUS320	No
Die Attach Material	HR9004-20 (PFAS-Free)	HR9004-20 (PFAS-Free)	EM760L2-P (PFAS-Free)	Yes
Wire Material	CuPdAu	CuPdAu	CuPdAu	No
Molding Compound Material	G750E	G750E	G750E	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 19 October 2026 (date code: 2643)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2025					**>**	**September 2026**					**October 2026**			
Work Week	27	28	29	30	31		36	37	38	39	40	41	42	43	44
Initial PCN Issue Date				X											
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: July 22, 2025: Issued initial notification.
September 17, 2026: Issued final notification. Added the "Change (Yes/No) column to the Pre- and Post- Change Summary table. Updated the affected parts list to add CEC1712H-S2-I/SX-KM0 catalog part number (CPN). Attached the Qualification Report. Provided estimated first ship date to be on October 19, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-15RYZV597_Qualification Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

MFOL-15RYZV597 - CCB 7657 Final Notice: Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

Affected Catalog Part Numbers (CPN):

CEC1712H-S2-I/SX-DE2

CEC1712H-S2-I/SX

CEC1712H-S2-I/SX-GM

CEC1712H-N2-I/SX-BMGP2

CEC1712H-N2-I/SX-BMGP3

CEC1712H-N2-I/SX-BMGP1

CEC1712H-N2-I/SX

CEC1712H-N2-I/SX-LU1

CEC1712H-B2-I/SX

CEC1702Q-B1-SX-CN2

CEC1702Q-B2-E/SXVAO

CEC1712H-N2-I/SX-TG1

CEC1702Q-S1-I/SX

CEC1702Q-B1-SX-TR

CEC1702Q-C2-I/SX

CEC1702Q-B1-SX

CEC1712H-S2-E/SXVAO

CEC1702Q-B2-I/SX-SM1

CEC1712H-S2-I/SX-KM0

CEC1702Q-B2-I/SX

CEC1702Q-B1-SX-CN1

CEC1702Q-C1-SX

CEC1712H-N2-I/SX-BMGP1-TR

CEC1712H-S2-I/SX-DE2-TR

CEC1712H-N2-I/SX-DL1



Qualification Report Summary
RELIABILITY LABORATORY

PCN #: MFOL-15RYZV597

Date:

September 4, 2026

Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of ATP7 as an additional assembly site for CEC1702 and CEC1712 device families available in 84L WFBGA (7x7x0.8mm) package.

QUAL ID:	R2600325
QUAL ID Rev.:	A
MP CODE:	SG0037SXXDEB
Part No.:	CEC1702Q-B2-I/SX
Bonding No.:	BD-003425-01
CCB No.:	7657

Substrate

Core Material:	HL832NXA
Core Thickness:	UMTC & GTS
Process	STD
L1/L2 Thickness	0.012/0.012mm
SM Material:	AUS320
SM Thickness:	0.02/0.02 mm
Part Number:	101395130
Drill Size:	100um
Line/Space Specs:	40um/40um

Bond Wire

Wire:	CuPdAu

Die Attach Material

Epoxy:	EM760L2-P
Conductive:	No

Mold Compound

Mold Compound:	G750E

Package

Type:	WFBGA
Pin/Ball Count:	84
Package Size:	7x7x0.8mm
Ball Pitch/Size:	0.65/0.25 mm
Solder Ball Material:	SAC105

Manufacturing Information

Assembly Lot No.
ATP7264400001.000
ATP7264400002.000
ATP7264400003.000

Result: **Pass**

Conclusion:
Qualification of SG003 mask / CEC1702Q-B2-I/SX product / CuPdAu wire in 84L WFBGA 7x7x0.8mm (SXX) package at ATP7 site is qualified for MSL3 at 260C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C Electrical Test **System:** LTX_D1X 25°C and 125°C	JESD22-A113 JEDEC J-STD-020	693(0)	0/693	Pass
High Temp Storage	175°C / 500 hours Electrical Test **System:** LTX_D1X 25°C and 125°C	JESD22-A103	135(0)	0/135	Pass
	175°C / 500 hours - WBS		9(0)	0/9	Pass
High Temp Storage	175°C / 1000 hours Electrical Test **System:** LTX_D1X 25°C and 125°C	JESD22-A103	132(0)	0/132	Pass
	175°C / 1000 hours - WBS		9(0)	0/9	Pass
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles Electrical Test **System:** LTX_D1X 125°C	JESD22-A104	231(0)	0/231	Pass
	-55°C / +150°C Air to Air / 1000 Cycles - WBP		9(0)	0/9	Pass
	-55°C / +150°C Air to Air / 1000 Cycles - WBS		9(0)	0/9	Pass
Temperature Cycling	-55°C / +150°C Air to Air / 2000 Cycles Electrical Test **System:** LTX_D1X 125°C	JESD22-A104	210(0)	0/210	Pass
	-55°C / +150°C Air to Air / 2000 Cycles - WBP		9(0)	0/9	Pass
	-55°C / +150°C Air to Air / 2000 Cycles - WBS		9(0)	0/9	Pass

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: PS1=3.3V Electrical Test **System:** LTX_D1X 25°C and 125°C	JESD22-A110	231(0)	0/231	Pass
	+130°C / 85%RH / 96 hours / Bias Voltage: PS1=3.3V - WBP		9(0)	0/9	Pass
	+130°C / 85%RH / 96 hours / Bias Voltage: PS1=3.3V - WBS		9(0)	0/9	Pass
Biased HAST	+130°C / 85%RH / 192 hours / Bias Voltage: PS1=3.3V Electrical Test **System:** LTX_D1X 25°C and 125°C	JESD22-A110	210(0)	0/210	Pass
	+130°C / 85%RH / 192 hours / Bias Voltage: PS1=3.3V - WBP		9(0)	0/9	Pass
	+130°C / 85%RH / 192 hours / Bias Voltage: PS1=3.3V - WBS		9(0)	0/9	Pass
Unbiased HAST	+130°C / 85%RH / 96 hours Electrical Test **System:** LTX_D1X 25°C	JESD22-A118	231(0)	0/231	Pass
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	30(0)	0/30	Pass
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5(0)	0/5	Pass
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5(0)	0/5	Pass
Solder Ball Shear	Bond Strength Data Assembly	AEC Q100-010, AEC Q003	30(0)	0/30	Pass